

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Eung San Cho	05/18/2011
RECEIVING PARTY DATA	
Name:	International Rectifier Corporation
Street Address:	101 N. Sepulveda Blvd.
City:	El Segundo
State/Country:	CALIFORNIA
Postal Code:	90245
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13969546
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ATTORNEY DOCKET NUMBER:	0400664D1
NAME OF SUBMITTER:	Michael Farjani
Signature:	/MF/
Date:	08/17/2013
Total Attachments: 2 source=0400664D1 Assignment for 13 969,546#page1.tif source=0400664D1 Assignment for 13 969,546#page2.tif	

OP \$40.00 13969546

ASSIGNMENT

WHEREAS, I/WE:

INVENTOR NAME	INVENTOR RESIDENCE ADDRESS
Eung San Cho	23500 Anza Ave. Unit #A; Torrance, CA 90505

have invented certain new and useful improvements disclosed in an application for United States Letters Patent titled "THERMALLY ENHANCED SEMICONDUCTOR PACKAGE WITH EXPOSED PARALLEL CONDUCTIVE CLIP," filed herewith, or filed on May 19, 2011, Serial No. 13/111,812, and identified by Docket No. 0400664 in the offices of FARJAMI & FARJAMI LLP;

AND WHEREAS INTERNATIONAL RECTIFIER CORPORATION, a Delaware corporation (hereinafter, together with any successors, legal representatives and assigns thereof, called "Assignee"), wants to acquire the entire right, title, and interest in and to said improvements and application:

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I/WE have sold, assigned, transferred and set over, and do hereby sell, assign, transfer and set over to Assignee the entire right, title, and interest in and to said improvements, and said application and all divisions, substitutions, continuations and continuations-in-part thereof, and all United States Letters Patents which may be granted thereon and all reissues and extensions thereof, and all priority rights under the International Convention for the Protection of Industrial Property for every member country, and all applications for patents (including related rights such as utility-model registrations, inventor(s) certificates, and the like), heretofore or hereafter filed for said improvements in any foreign countries, and all patents (including all extensions, renewals, and reissues thereof) granted for said improvements in any foreign countries; and I/WE hereby authorize and request the United States Commissioner of Patents and Trademarks, and any officials of foreign countries whose duty it is to issue patents on applications as aforesaid, to issue all patents for said improvements to Assignee in accordance with the terms of this assignment.

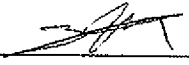
Each of the undersigned hereby authorizes and requests the Commissioner of Patents and Trademarks to issue said Letters Patents to Assignee.

Each of the undersigned hereby authorizes the attorneys of record in said application to insert in this assignment the filing date and serial number of said application when officially known.

Each of the undersigned warrants himself/herself to be the owner of the entire right, title and interest in said invention or improvements and to have the full right to make this assignment, and further warrants that there are no outstanding prior assignments, licenses, or other encumbrances on the interest herein assigned, and will not execute any agreement in conflict herewith;

AND I/WE HEREBY further covenant and agree that I/WE will communicate to Assignee any facts known to me/us respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, continuations-in-part, re-examination, extension, substitute and reissue applications, make all rightful oaths, and generally do everything possible to aid Assignee to obtain and enforce proper patent protection for said improvements in all countries.

I hereunto set my hand this 18th day of May, 2011.



EUNG SAN CHO